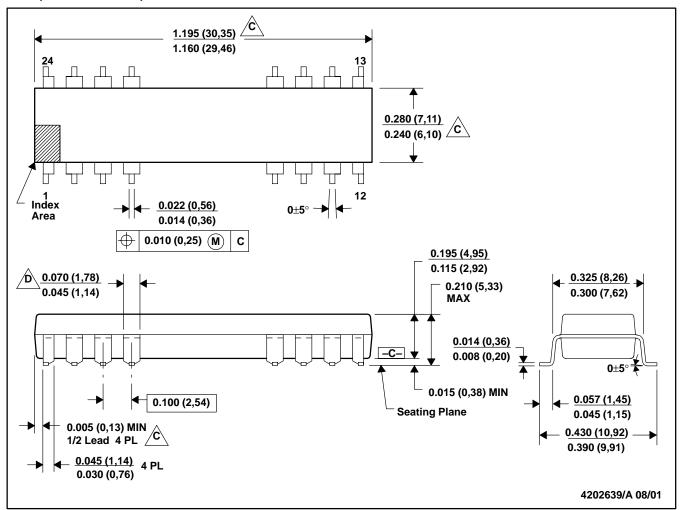
MECHANICAL DATA

MPDS102 - AUGUST 2001

DVL (R-PDSO-T16/24)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- \dot{c} Dimensions do not include mold flash or protrusions. A Mold flash or protrusions shall not exceed 0.010 (0,25).
- D. Maximum dimension does not include dambar
 - protrusions. Dambar protrusions shall not exceed 0.010 (0,25).
- E. Distance between leads including dambar protrusions to be 0.005 (0,13) minimum.
- F. A visual index feature must be located within the cross-hatched area.
- G. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.
- H. Controlling dimension in inches.



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